

Technical Data Sheet

KES-3070

Biphenyl aralkyl type epoxy

General Description

KES-3070 provides excellent thermal stability and self-extinguishing characteristics when used in electrical laminate formulation. KES-3070's low softening point and high flow property allows user to add large amount of inorganic filler to increase mechanical and thermal stability of final product. Low moisture absorption property of KES-3070 makes final product more reliable in a humid condition.

Resin Properties

Property	Typical values
EEW(g/eq)	270~310
Hy-Cl(ppm)	500 max.
Softening point(°C) (Ball&ring,5°C/min.)	65~75
Melt viscosity (P) (ICI, 150°C)	2.0~4.0

Characteristics

1. Excellent thermal stability when cured with proper curing agent
2. Low moisture uptake in humid condition
3. Low softening point (< 80°C) and melt viscosity
4. Excellent toughness for severe mechanical process

Storage

Keep in cool, dry, ventilate condition and in closed containers.

Keep away from heat sources and direct sunlight. Recommended safe handling procedures are discussed in the information on the MSDS should reviewed and understood before working.

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Properties		KES-3070	Competitor's
Resin Properties	Softening point (°C) ¹⁾	66.7	69.0
	Mw (g/mol)	1810	1880
	EEW (g/eq)	291.1	289.5
	Hy-Cl (ppm)	280.1	290.5
	Viscosity (Pa.s) ²⁾	0.27	0.31

1) Ball & ring. 5°C/min.

2) ICI viscometer, 150°C

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